

**DESIGNED AND DIMENSIONED IN MILLIMETERS[INCHES]
ALL DIMENSIONS REFERENCE**

DO NOT SCALE FROM THIS PRINT

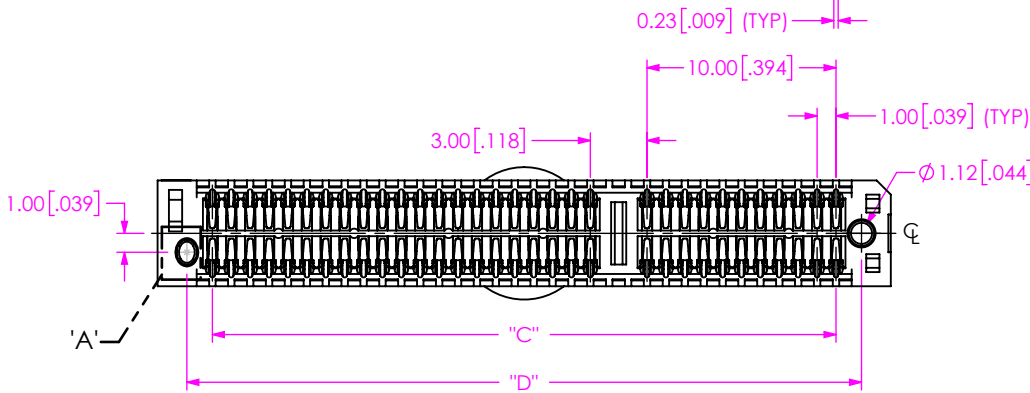
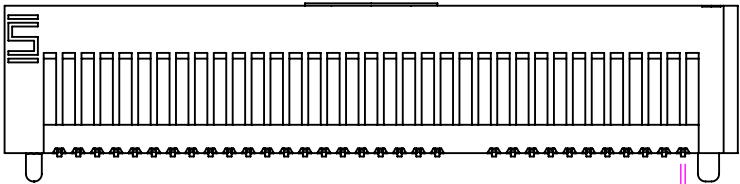
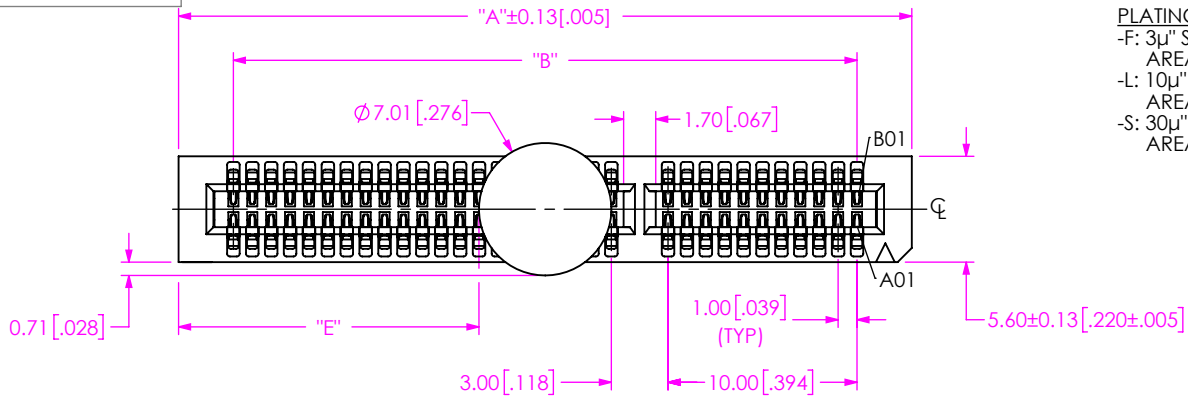


FIG 1
PCIE-G4-04-01-X-DV-A-K SHOWN

- NOTES:
1. MATING CARD MUST HAVE LEAD-IN. SEE SAMTEC FOOTPRINT FOR SPECIFICATIONS.
 2. -01, -04, -08 LANES TAPE & REEL IS STANDARD PACKAGING, -16 LANES TRAY IS STANDARD PACKAGING.
 3. ORDERS WILL BE PACKAGED ACCORDING TO THE SAMTEC PACKAGING EFFICIENCY STANDARDS (SPES) FOUND ON WWW.SAMTEC.COM.
 4. K-DOT PROVIDED AS STANDARD.
 5. PART MUST HAVE EITHER -A OR -WT AS REQUIRED, -A NOT AVAILABLE WITH -WT OPTION.
 6. NOTE DELETED.
 7. ATTACH LABEL TO EACH REEL.

PCIE-G4-XX-XX-X-DV-XX-K-XX

No OF LANES
-01, -04, -08, -16

CARD THICKNESS
-01: FOR 1.57[.062] CARD

PLATING SPECIFICATION
-F: 3µ" SELECTIVE GOLD IN CONTACT AREA, MATTE TIN ON TAIL
-L: 10µ" SELECTIVE GOLD IN CONTACT AREA, MATTE TIN ON TAIL
-S: 30µ" SELECTIVE GOLD IN CONTACT AREA, MATTE TIN ON TAIL

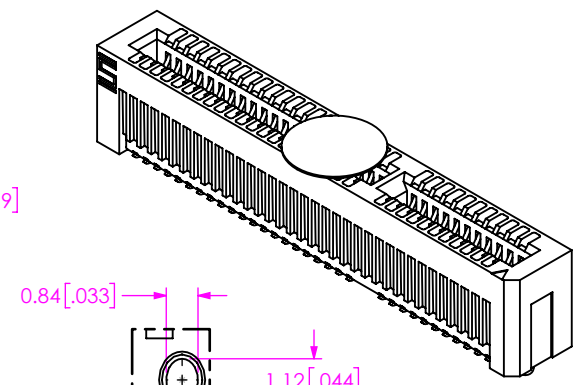
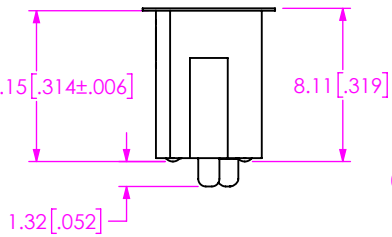
ROW SPECIFICATION
-DV: DOUBLE VERTICAL

PACKAGING
BLANK: TRAY (SEE NOTES 2 & 3)
(ONLY AVAILABLE FOR LANES -16)
-TR: TAPE & REEL (SEE NOTES 2, 3 & 7)
(REQUIRED FOR LANES -01, -04, & -08)
-FR: FULL REEL QTY TAPE & REEL
(SEE NOTES 2, 3 & 7)
(REQUIRED FOR LANES -01, -04, & -08)

PICK & PLACE OPTION
-K: POLYIMIDE FILM PAD
(SEE NOTE 4)

OPTION
-A: ALIGNMENT PIN (SEE FIG 1 & NOTE 5)
■ -WT: WELD TAB
(SEE FIG 2, SHT 2 & NOTE 5)

■ NOT AVAILABLE WITH -A OPTION.



DETAIL 'A'
SCALE 5 : 1

No Of LANES	"A"	"B"	"C"	"D"	"E"
-01	24.80 [0.976]	19.00 [0.748]	19.00 [0.748]	21.70 [0.854]	8.89 [0.350]
-04	38.80 [1.528]	33.00 [1.299]	33.00 [1.299]	35.70 [1.406]	15.89 [0.626]
-08	55.80 [2.197]	50.00 [1.969]	50.00 [1.969]	52.70 [2.075]	24.39 [0.960]
-16	88.80 [3.496]	83.00 [3.268]	83.00 [3.268]	85.70 [3.374]	40.89 [1.610]

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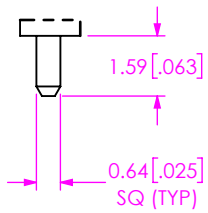
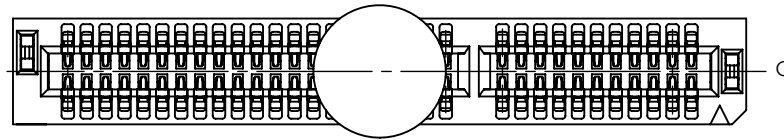
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SHEET SCALE: 2:5:1

MATERIAL:
INSULATOR: LCP
CONTACT: COPPER ALLOY
WELD TAB: COPPER ALLOY

samtec

520 PARK EAST BLVD, NEW ALBANY, IN 47150
PHONE: 812-944-6733 FAX: 812-948-5047
e-Mail info@SAMTEC.com code 55322

DESCRIPTION:
1.00mm DV HIGH SPEED EDGE CARD ASSEMBLY
DWG. NO.
PCIE-G4-XX-XX-X-DV-XX-K-XX
BY: D.SCHMELZ 10/11/2018 SHEET 1 OF 2



DETAIL 'B'
SCALE 5 : 1

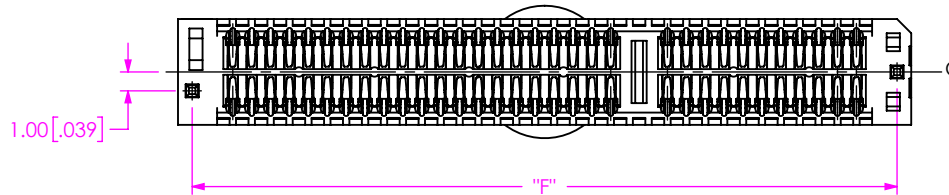
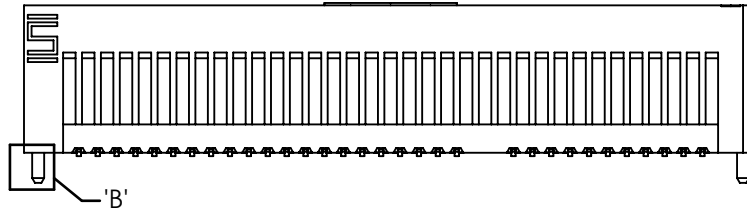


FIG 2
PCIE-G4-04-01-X-DV-WT-K SHOWN
(DIFFERENT AS SHOWN, OTHERWISE SAME AS FIG 1)

No OF LANES	"F"
-01	23.30 [0.917]
-04	37.30 [1.469]
-08	54.30 [2.138]
-16	87.30 [3.437]

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PCIE-G4-XX-XX-X-DV-XX-K-XX

BY: D.SCHMELZ 10/11/2018 SHEET 2 OF 2